

Docket: CS 99 - 065
S/N: 09/442,499



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To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

From: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

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MAR 06 2002
TC 1700

Serial No.: 09/442,499 Filed: 11/18/99
Inventor: Ho

Title: Plasma Etch Method For Forming Plasma Etched Silicon
Layer

Group Art Unit: 1763 Examiner: Goudreau, G.
Attorney Docket: CS 99 - 065

H/C
3/18/02
MW

RESPONSE TO PATENT OFFICE ACTION

Dear Sir:

In response to the office action dated 11/07/01, please consider the
following remarks:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the
United States Postal Service as first class mail in an envelope addressed to:
Commissioner of Patent and Trademarks, Washington, D.C. 20231, on
February 1, 2002.

Signature/Date


2/1/02
Stephen B. Ackerman, Reg #37,761